

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Ching-Lin Fan	12/27/2010
Ping-Cheng Chiu	12/27/2010
Chang-Chih Lin	12/27/2010
RECEIVING PARTY DATA	
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13006424
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Total Attachments: 2 source=36544US_ASSGN#page1.tif source=36544US_ASSGN#page2.tif	

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PATENT
REEL: 025646 FRAME: 0513

ASSIGNMENT

WHEREAS,

1. Ching-Lin Fan

2. Ping-Cheng Chiu

3. Chang-Chih Lin

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **METHODS OF FORMING HYDROPHOBIC SILICON DIOXIDE LAYER AND FORMING ORGANIC THIN FILM TRANSISTOR**

[] Filed:

Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, National Taiwan University of Science and Technology
of #43, Sec. 4, Keelung Rd., Taipei, 106, Taiwan, R.O.C

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Ching-Lin Fan
Sole or First Joint Inventor: Ching-Lin Fan

Date: Dec. 27, 2010

Signature: Ping-Cheng Chiu
Second Joint Inventor (if any): Ping-Cheng Chiu

Date: Dec. 27, 2010

Signature: Chang-Chih Lin
Third Joint Inventor (if any): Chang-Chih Lin

Date: Dec. 27, 2010